

# SOT754-2

plastic thin fine-pitch ball grid array package; 256 balls, 0.8 mm pitch, 15 mm x 15 mm x 0.71 mm body

11 October 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	TFBGA256
<b>Package type industry code</b>	TFBGA256
<b>Package style descriptive code</b>	TFBGA (thin fine-pitch ball grid array)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-216
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	27-10-2009
<b>Manufacturer package code</b>	SOT754

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	14.9	15	15.1	mm
package width	14.9	15	15.1	mm
seated height	0.95	1.06	1.2	mm
package height	0.65	0.71	0.8	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	256	-	



## 2 Package outline

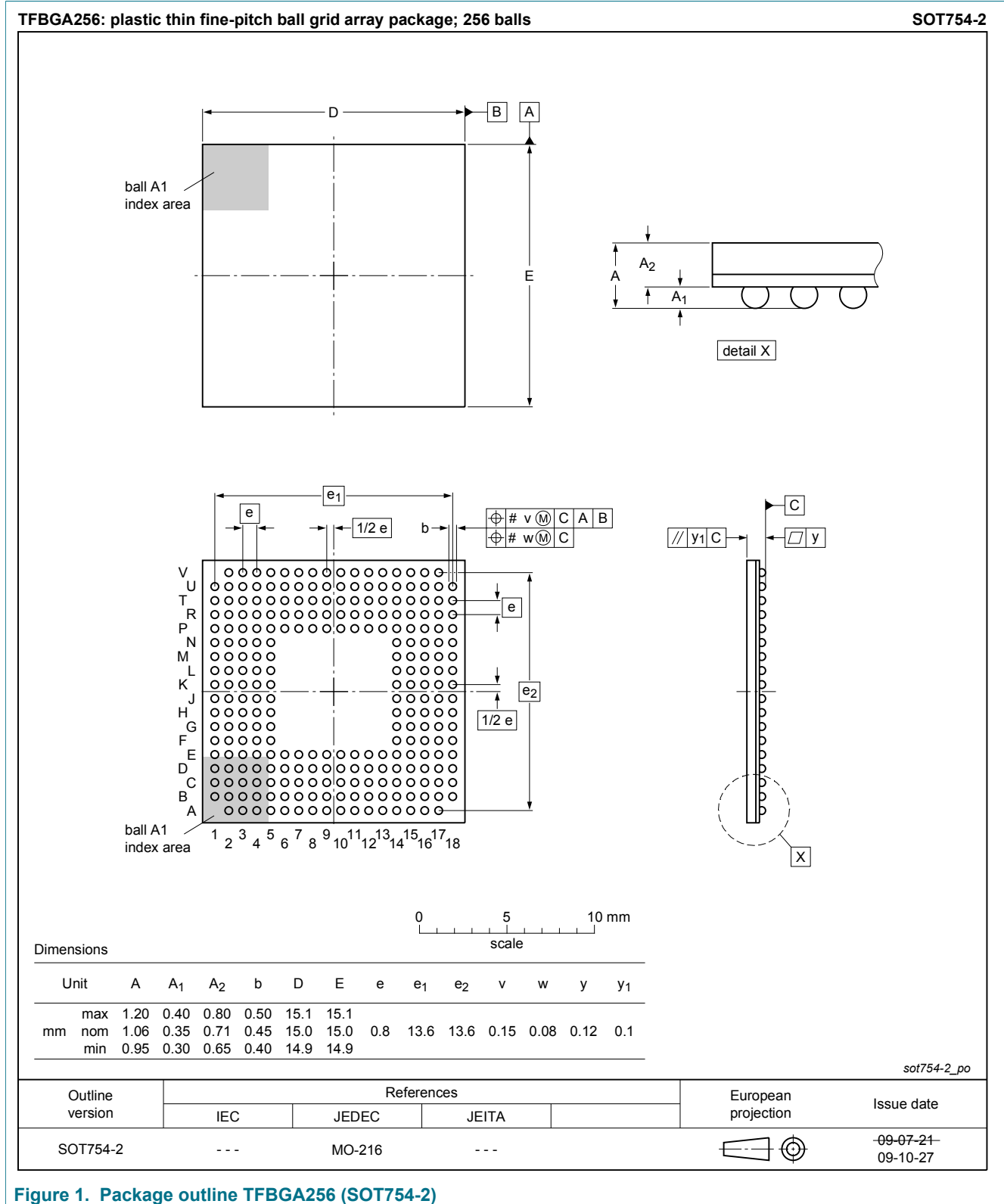


Figure 1. Package outline TFBGA256 (SOT754-2)

### 3 Legal information

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Contents

1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....3